

# **CX1SM AT CRYSTAL**

8 MHz to 250 MHz Miniature Surface Mount AT Quartz Crystal

> Fundamental Mode: 8 MHz - 250 MHz Third Overtone Mode: 48 MHz - 160 MHz

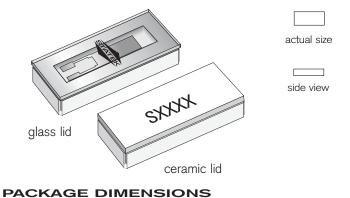
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# DESCRIPTION

STATEK's miniature CX1SM AT crystals in leadless ceramic packages are designed for surface mounting on printed circuit boards or hybrid substrates. Due to its robust design, this product has gained wide acceptance in the industry.



TOP

B<sup>-</sup>

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## FEATURES

- Designed for surface mount applications using infrared, vapor phase, or epoxy mount techniques
- Low profile hermetically sealed ceramic package
- Excellent aging characteristics
- Available with glass or ceramic lid
- High shock and vibration resistance
- Custom designs available
- Full military testing available
- Designed and manufactured in the USA

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APPLICATIONS					
Medical		TYP	ICAL	MAX	IMUM
	DIM	inches	mm	inches	mm
Infusion Pumps	А	0.315	8.00	0.330	8.38
Monitoring Equipment	В	0.140	3.56	0.155	3.94
Industrial, Computer & Communications	С	see b		below	
Instrumentation	D	0.045	1.14	0.055	1.40
Process Control	E	0.060	1.52	0.070	1.78
Environmental Control					
Telemetry					
Military & Aerospace	тн	ICKNES	S (DIM	C) MAXI	мим

Communications		GLASS LID		CERAMIC LID	
Satellite Command and Control		inches	mm	inches	mm
Cockpit Electronics	SM1	0.065	1.65	0.070	1.78
Smart Munitions	SM2/SM4	0.067	1.70	0.072	1.83
Timing Devices (Fuzes)	SM3/SM5	0.070	1.78	0.075	1.90

10107 - Rev B

SGS



#### SPECIFICATIONS

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice.

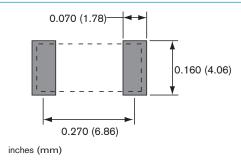
Fundamental Frequency	<u>10 MHz</u>	<u>32 MHz</u>	<u>155.52 MHz</u>
Motional Resistance $R_1(\Omega)$	30	25	15
Motional Capacitance $C_1$ (fF)	5.5	6.2	4.0
Quality Factor Q (k)	100	30	30
Shunt Capacitance $C_0$ (pF)	2.2	2.3	2.3
Calibration Tolerance <sup>1</sup>	± 100 pp	m, or tighte	er as required
Load Capacitance <sup>2</sup>	20 pF for	f ≤ 50 MH	Ηz
	10 pF for	f > 50 MH	Ηz
Drive Level	500 µW	MAX for f <u>s</u>	≤ 50 MHz
	200 µW	MAX for f :	> 50 MHz
Frequency-Temperature Stability <sup>1,3</sup>	± 100 pp	m to ±20	ppm (Commercial) ppm (Industrial) ppm (Military)
Aging, first year⁴	5 ppm M	AX (better th	an 1ppm available)
Shock, survival⁵	3,000 g, (	0.3 ms, 1/	2 sine
Vibration, survival <sup>6</sup>	20 g, 10-	2,000 Hz s	swept sine
Operating Temp. Range	-40°C to -	+70°C (Ca +85°C (In +125°C (M	dustrial)
Storage Temp. Range	-55°C to -	+125°C	
Max Process Temperature	260°C for	20 sec.	

#### TERMINATIONS

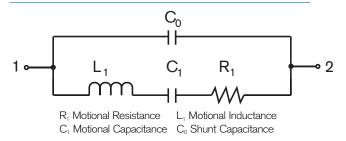
<b>Designation</b>	Termination
SM1	Gold Plated (Lead Free)
SM2	Solder Plated
SM3	Solder Dipped
SM4	Solder Plated (Lead Free)
SM5	Solder Dipped (Lead Free)

Max Process Temperature 260°C for 20 sec.

### SUGGESTED LAND PATTERN

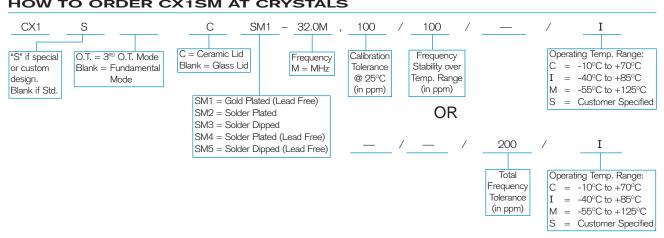


## **EQUIVALENT CIRCUIT**



#### PACKAGING OPTIONS

- Tray Pack
- 16mm tape, 7" or 13" reels Per EIA 481 (see Tape and Reel data sheet 10109)



#### HOW TO ORDER CX1SM AT CRYSTALS

5. Higher shock version available. Refer to data sheet model CX1HGSM AT (10108). 6. Per MIL-STD-202G, Method 204D, Condition D. Random vibration testing also available.

3. Does not include calibration tolerance. The characteristics of the frequency stability over

4. 5 ppm MAX for frequencies below 40 MHz. For tighter tolerances and higher frequencies

1. Other tolerances available. Contact factory.

temperature follow that of the AT thickness-shear mode.

2. Unless specified otherwise.

contact factory.

